

IR2137/IR2237(J)(Q)

Features

- Floating channel up to +600V or +1200V
- “soft” over-current shutdown turns off all six outputs
- Integrated high side desaturation circuit
- Controlled “soft” turn on for EMI reduction
- Integrated brake IGBT driver
- Three independent low side COM pins
- Separate pull-up/pull-down output drive pins
- Matched delay outputs
- 3.3V logic compatible
- Under voltage lockout with hysteresis band

Description

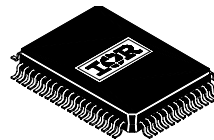
The IR2137/IR2237(J)(Q) are a high voltage, high speed 3-phase IGBT driver best suited for AC motor drive applications. Integrated desaturation logic provides ground fault protection as well as other mode of over current protection. Soft shutdown is initiated in the event of any overcurrent/ground fault conditions, and all six outputs are simultaneously turned off. Output drivers have separate turn on/off pins to facilitate independent gate drive impedance with EMI soft turn on. Optimum matched delays between phases, and between high/low side enables small deadtime, thus improving low speed performance. The brake driver eliminates additional circuits.

3-PHASE BRIDGE DRIVER

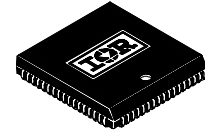
Product Summary

V_{OFFSET}	600V max. or 1200V max.
$I_{O+/-}$	220mA / 460mA
V_{OUT}	12.5V - 20V
Brake $I_{o+/-}$	40mA/80mA
Matched delay	75nsec
Deadtime (typ.)	300 nsec
DESAT Blanking time (typ.)	2.0usec
DESAT input voltage threshold (typ.)	$V_{t+} = 5.0V$

Packages

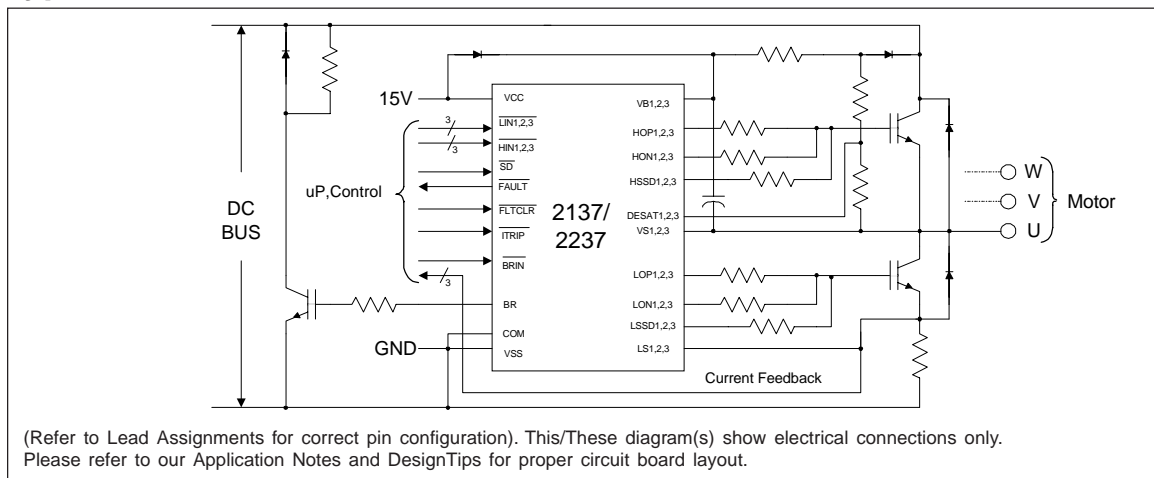


64-Lead MQFP



68-Lead PLCC

Typical Connection



IR2137/IR2237(J)(Q)

Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition	Min.	Max.	Units
V _{S1,2,3}	High side offset voltage	V _{B1,2,3} - 25	V _{B1,2,3} + 0.3	V
V _{B1,2,3}	High side floating supply voltage (IR2137) (IR2237)	-0.3 -0.3	625 1225	
V _{HO}	High side floating output voltage (HOP, HON, HSSD)	V _{S1,2,3} - 0.3	V _{B1,2,3} + 0.3	
V _{CC}	Low side and logic fixed supply voltage	-0.3	25	
V _{SS}	Logic ground	V _{CC} - 25	V _{CC} + 0.3	
V _{LO1,2,3}	Low side output voltage (LOP, LON, LSSD)	V _{LS1,2,3} - 0.3	V _{CC} + 0.3	
V _{IN}	Logic input voltage ($\overline{\text{HIN}}$, $\overline{\text{LIN}}$, $\overline{\text{SD}}$, $\overline{\text{ITRIP}}$, $\overline{\text{FLTCLR}}$, $\overline{\text{BRIN}}$)	V _{SS} - 0.3	V _{SS} + 15	
V _{FLT}	FAULT output voltage	V _{SS} - 0.3	V _{CC} + 0.3	
V _{DESAT}	DESAT input voltage	V _{S1,2,3} - 0.3	V _{B1,2,3} + 0.3	
V _{BR}	BRAKE output voltage	- 0.3	V _{CC} + 0.3	
V _{LS1,2,3}	Low side output return voltage	V _{CC} - 25	V _{CC} + 0.3	
dV/dt	Allowable offset supply voltage slew rate	—	50	
P _D	Package power dissipation @ T _A ≤ +25°C (MQFP64) (PLCC68)	—	2.0	W
		—	3.0	
R _{thJA}	Thermal resistance, junction to ambient (MQFP64) (PLCC68)	—	60	°C/W
		—	40	
T _J	Junction temperature	—	150	°C
T _S	Storage temperature	-55	150	
T _L	Lead temperature (soldering, 10 seconds)	—	300	

Recommended Operating Conditions

The Input/Output logic timing diagram is shown in figure 1. For proper operation the device should be used within the recommended conditions. All voltage parameters are absolute voltages referenced to COM. The V_S offset rating is tested with all supplies biased at 15V differential.

Symbol	Definition	Min.	Max.	Units
V _{B1,2,3}	High side floating supply voltage	V _{S1,2,3} + 13	V _{S1,2,3} + 20	V
V _{S1,2,3}	High side floating supply offset voltage (IR2137) (IR2237)	Note 1 Note 1	600 1200	
V _{HO1,2,3}	High side output voltage (HOP, HON, HSSD)	V _{S1,2,3}	V _{S1,2,3} + 20	
V _{LO1,2,3}	Low side output voltage (LOP, LON, LSSD)	V _{LS1,2,3}	V _{CC}	
V _{CC}	Low side and logic fixed supply voltage	12.5	20	
V _{SS}	Logic ground	-5	+5	
V _{IN}	Logic input voltage ($\overline{\text{HIN}}$, $\overline{\text{LIN}}$, $\overline{\text{SD}}$, $\overline{\text{ITRIP}}$, $\overline{\text{FLTCLR}}$, $\overline{\text{BRIN}}$)	V _{SS}	V _{SS} + 5	
V _{BR}	BRAKE output voltage	0	V _{CC}	
V _{FLT}	FAULT output voltage	V _{SS}	V _{CC}	
V _{LS1,2,3}	Low side output return voltage	-5.0	+5.0	
V _{DESAT}	DESAT pin input voltage	V _{S1,2,3}	V _{B1,2,3}	
T _A	Ambient temperature	-40	125	

Note 1: Logic operational for V_S of COM -5 to COM +600V/+1200V. Logic state held for V_S of COM -5V to -COM V_{BS}.

Note 2: All input pins are internally clamped with a 5.2V zener diode.

Static Electrical Characteristics

V_{BIAS} (V_{CC} , $V_{BS1,2,3}$) = 15V and $T_A = 25^\circ\text{C}$ unless otherwise specified. The V_{IN} , V_{TH} and I_{IN} parameters are referenced to V_{SS}/COM and are applicable to all six channels (HOP/HON1,2,3 and LOP/LON1,2,3). The V_O and I_O parameters are referenced to $V_{LS1,2,3}$ and $V_{S1,2,3}$ and are applicable to the respective output leads: $HO_{1,2,3}$ and $LO_{1,2,3}$. V_{DESAT} and I_{DESAT} parameters are referenced to $V_{S1,2,3}$

Symbol	Definition	Min.	Typ.	Max.	Units	Test Conditions
V_{CCUV+}	V_{CC} supply undervoltage positive going threshold	10.3	11.4	12.5	V	
V_{CCUV-}	V_{CC} supply undervoltage negative going threshold	9.5	10.4	11.3		
V_{CCUVH}	V_{CC} supply undervoltage lockout hysteresis	—	1.0	—		
V_{BSUV+}	V_{BS} supply undervoltage positive going threshold	10.3	11.4	12.5		
V_{BSUV-}	V_{BS} supply undervoltage negative going threshold	9.5	10.4	11.3		
V_{BSUVH}	V_{BS} supply undervoltage lockout hysteresis	—	1.0	—		
I_{LK}	Offset supply leakage current (IR2137)	—	—	50	μA	$V_{B1,2,3} = V_{S1,2,3} = 600\text{V}$
	(IR2237)	—	—	50		$V_{B1,2,3} = V_{S1,2,3} = 1200\text{V}$
I_{QBS}	Quiescent V_{BS} supply current	—	120	200	V	$V_{CC} = 12.5$ to 20V
I_{QCC}	Quiescent V_{CC} supply current	—	2	6		
V_{IH}	Logic "0" input voltage (OUT=LO) (\overline{HIN} , \overline{LIN} , \overline{ITRIP} , \overline{SD} , \overline{BRIN} , \overline{FLTCLR})	3.15	—	—		
V_{IL}	Logic "1" input voltage (OUT=HI) (\overline{HIN} , \overline{LIN} , \overline{ITRIP} , \overline{SD} , \overline{BRIN} , \overline{FLTCLR})	—	—	0.8		
V_{t+}	Logic input positive going threshold (\overline{HIN} , \overline{LIN} , \overline{ITRIP} , \overline{SD} , \overline{BRIN} , \overline{FLTCLR})	1.6	2.5	3.1		
V_{t-}	Logic input negative going threshold (\overline{HIN} , \overline{LIN} , \overline{ITRIP} , \overline{SD} , \overline{BRIN} , \overline{FLTCLR})	0.9	1.5	2.4		
V_T	Logic input hysteresis (\overline{HIN} , \overline{LIN} , \overline{ITRIP} , \overline{SD} , \overline{BRIN} , \overline{FLTCLR})	0.7	1.0	—		
V_{OH}	High level output voltage, $V_{BIAS} - V_O$ (normal switching) HOP, LOP	—	—	100	mV	$I_O = 1\text{ mA}$
V_{OL}	Low level output voltage, V_O (normal switching) HON, LON	—	—	100		
I_{IN+}	Logic "1" input bias current	—	150	—	μA	$V_{IN} = 0\text{V}$
I_{IN-}	Logic "0" input bias current	—	80	—		$V_{IN} = 5\text{V}$
I_{DESAT+}	"high" DESAT input bias current	—	—	15		$V_{DESAT} = 15\text{V}$
I_{DESAT-}	"low" DESAT input bias current	—	—	.1		$V_{DESAT} = 0\text{V}$
I_{O+}	Output high short circuit pulsed current	220	300	—	mA	$V_O = 0\text{V}$, $V_{IN} = 0\text{V}$ $PW \leq 10\ \mu\text{s}$
I_{O-}	Output low short circuit pulsed current	460	550	—		$V_O = 15\text{V}$, $V_{IN} = 5\text{V}$ $PW \leq 10\ \mu\text{s}$

Static Electrical Characteristics - cont.

V_{BIAS} (V_{CC} , $V_{BS1,2,3}$) = 15V and T_A = 25°C unless otherwise specified. The V_{IN} , V_{TH} and I_{IN} parameters are referenced to V_{SS}/COM and are applicable to all six channels (HOP/HON1,2,3 and LOP/LON1,2,3). The V_O and I_O parameters are referenced to $V_{LS1,2,3}$ and $V_{S1,2,3}$ and are applicable to the respective output leads: HO1,2,3 and LO1,2,3. V_{DESAT} and I_{DESAT} parameters are referenced to $V_{S1,2,3}$

Symbol	Definition	Min.	Typ.	Max.	Units	Test Conditions
I_{OBR+}	BR output high short circuit pulsed current	40	75	—	mA	$V_{BR}=0V, V_{BRIN}=0V$ $PW \leq 10 \mu s$
I_{OBR-}	BR output low short circuit pulsed current	80	120	—		$V_{BR}=15V, V_{BRIN}=5V$ $PW \leq 10 \mu s$
V_{OHB}	BR high level output voltage, $V_{BIAS}-V_{BR}$	—	—	300	mV	$I_{BR} = 1mA$
V_{OLB}	BR low level output voltage, V_{BR}	—	—	150		
$R_{ON,SS}$	Soft shutdown on resistance	—	500	—	Ω	ITRIP = 0V
$R_{ON,FLT}$	FAULT low on resistance	—	60	—		
V_{DESAT+}	High DESAT input threshold voltage	—	5.2	—	V	

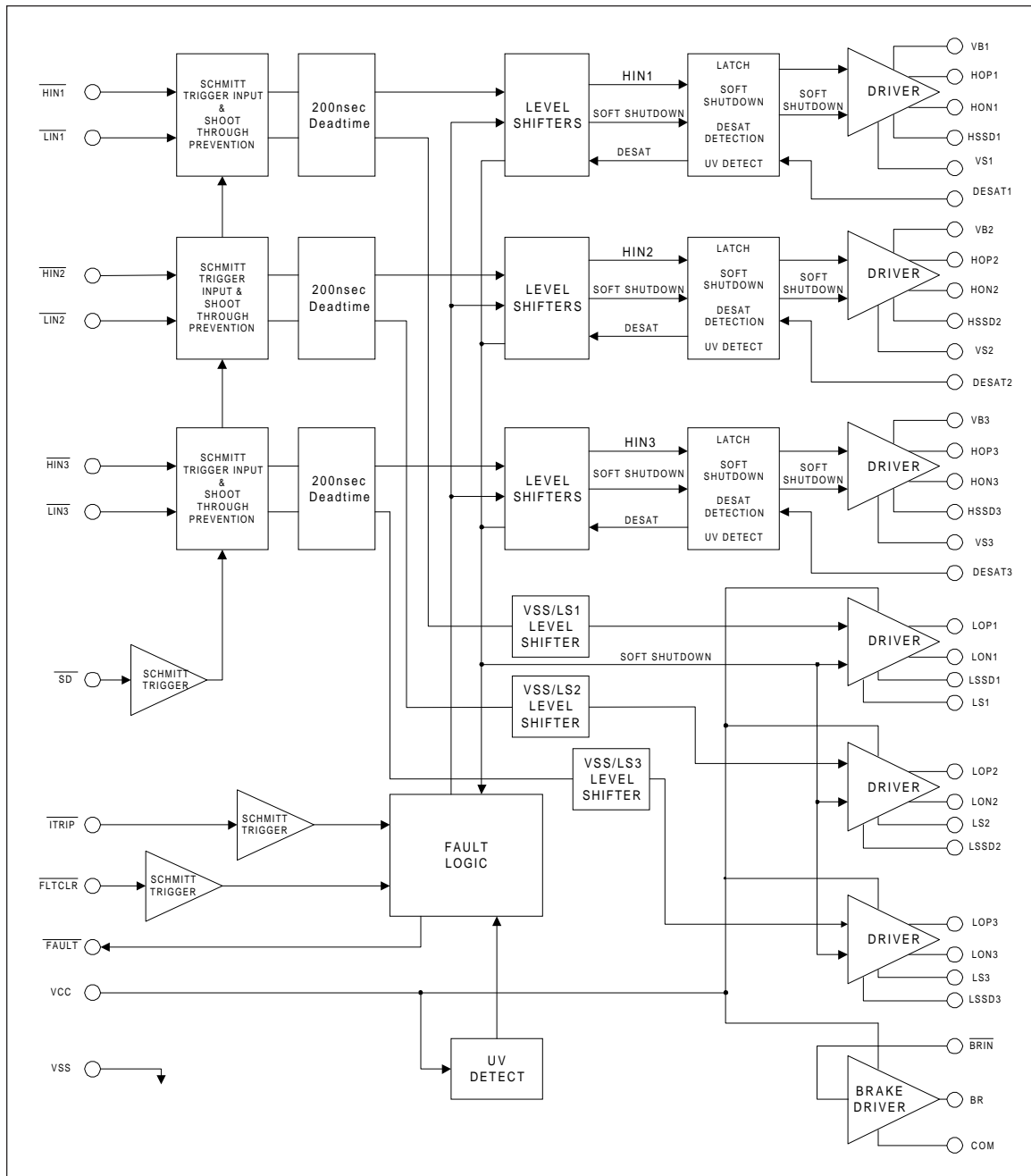
AC Electrical Characteristics

$V_{BIAS} (V_{CC}, V_{BS}) = 15V$, $V_{S1,2,3} = V_{SS}$, $T_A = 25^\circ C$ and $C_L = 1000$ pF unless otherwise specified.

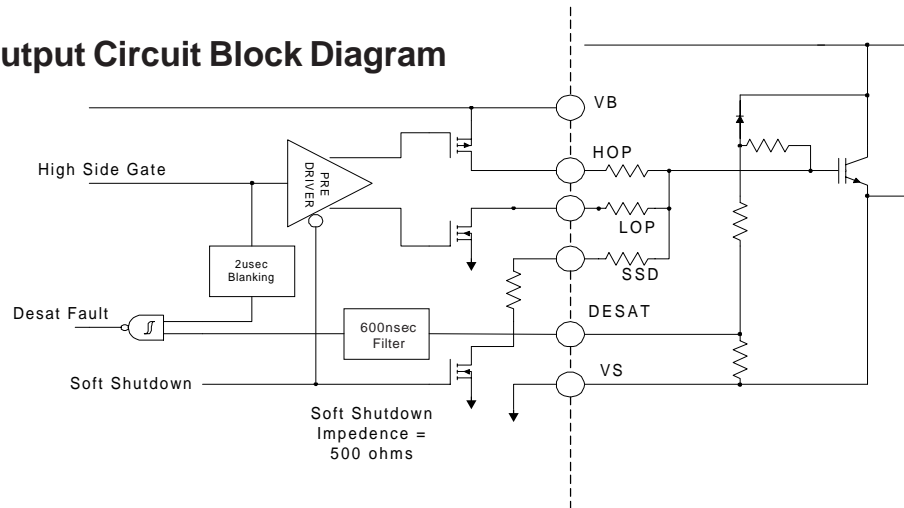
Symbol	Definition	Min.	Typ.	Max.	Units	Test Conditions	
Propagation Delay Characteristics							
t_{on}	Turn-on propagation delay	150	400	600	ns	$V_{IN} = 0$ & $5V$ $V_{S1,2,3} = 0$ to $600V$ or $1200V$ $HOP=HON, LOP=LON$ Figure 4	
t_{off}	Turn-off propagation delay	150	400	600			
t_r	Turn-on rise time	—	115	—			
t_f	Turn-off fall time	—	25	—			
t_{TRIP}	ITRIP to output shutdown propagation delay	—	1000	1400			$V_{IN}, V_{DESAT}=0$ $V_{SD} = 5V$
t_{SD}	SD to output shutdown propagation delay	—	1200	1500			$V_{IN}, V_{DESAT} = 0$ $V_{ITRIP} = 5V$, fig. 7
t_{DESAT1}	DESAT to output shutdown propagation delay at HOPx turn-on	1400	2800	4200			$V_{S1,2,3} = 0$ to $600V$ or $1200V$ $V_{HIN} = 0V$, $V_{SD}, V_{ITRIP} = 5V$, $V_{DESAT} = 15V$, fig. 5
t_{DESAT2}	DESAT to output shutdown propagation delay after blanking	600	1150	1700			$V_{IN}, V_{ITRIP} = 0V$, $V_{SD} = 5V$, $V_{DESAT} = 0V$, fig. 7
$t_{FLT, IT}$	ITRIP to FAULT output delay	—	800	1100			$V_{SD} = 5V$, $V_{DESAT} = 0V$, fig. 7
t_{FLTCLR}	FLTCLR to FAULT output delay	—	1100	1400			$V_{SD} = 5V$, $V_{DESAT} = 0V$, fig. 7
$t_{FLT, DESAT1}$	DESAT to FAULT output delay propagation delay at HOPx turn-on	—	2500	—			$V_{S1,2,3} = 0$ to $600V$ or $1200V$ $V_{IN} = 0V$, $V_{SD}, V_{ITRIP} = 5V$, $V_{DESAT} = 15V$, Figure 5
$t_{FLT, DESAT2}$	DESAT to FAULT output delay propagation delay after blanking	—	850	—			Figure 4
t_{BL}	DESAT blanking time at turn-on	—	2000	—			
t_{onBR}	BR output turn-on propagation delay	—	120	200			
t_{offBR}	BR output turn-off propagation delay	—	85	150			
t_{fBR}	BR output turn-off fall time	—	150	—			
Deadtime/Delay Matching Characteristics							
DT	Deadtime	—	300	—	ns	Figure 6	
MDT	Matching delay, max (t_{on}, t_{off}) - min (t_{on}, t_{off}), (t_{on}, t_{off} are applicable to all six channels)	—	0	75		External dead time >400nsec	
PM	Output pulse width matching, $IPWin - PWoutl$ (exclude BRIN/BR)	—	0	75		External dead time >400nsec, Fig. 4	

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Functional Block Diagram



Driver Output Circuit Block Diagram



Lead Definitions

Symbol	Description
V _{CC}	Low side and logic supply voltage
V _{SS}	Logic Ground
HIN _{1,2,3}	Logic inputs for high side gate driver outputs (HOP _{1,2,3} /HON _{1,2,3} , out of phase)
LIN _{1,2,3}	Logic inputs for low side gate driver outputs (LOP _{1,2,3} /LON _{1,2,3} , out of phase)
SD	Logic input for shutdown (hard shutdown, level sensitive signal, negative logic)
ITRIP	Logic input for overcurrent shutdown (soft shutdown, edge sensitive, negative signal)
FLTCLR	Logic input for FAULT clear (edge sensitive, negative signal)
BRIN	Logic input for brake driver, out of phase with BR
FAULT	Fault output indicates over current and desaturation shutdown (open drain)
BR	Brake driver output
COM	Brake driver return
VB _{1,2,3}	High side gate drive floating supply
HOP _{1,2,3}	High side driver pull up output
HON _{1,2,3}	High side driver pull down output
HSSD _{1,2,3}	High side soft shutdown output
DESAT _{1,2,3}	IGBT desaturation protection input
VS _{1,2,3}	High voltage floating supply return
LOP _{1,2,3}	Low side driver pull up output
LON _{1,2,3}	Low side driver pull down output
LSSD _{1,2,3}	Low side soft shutdown output
LS _{1,2,3}	Low side driver returns

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Lead Assignments

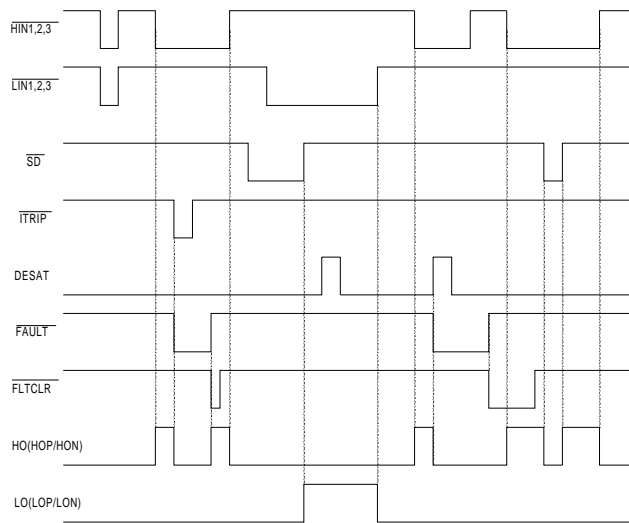
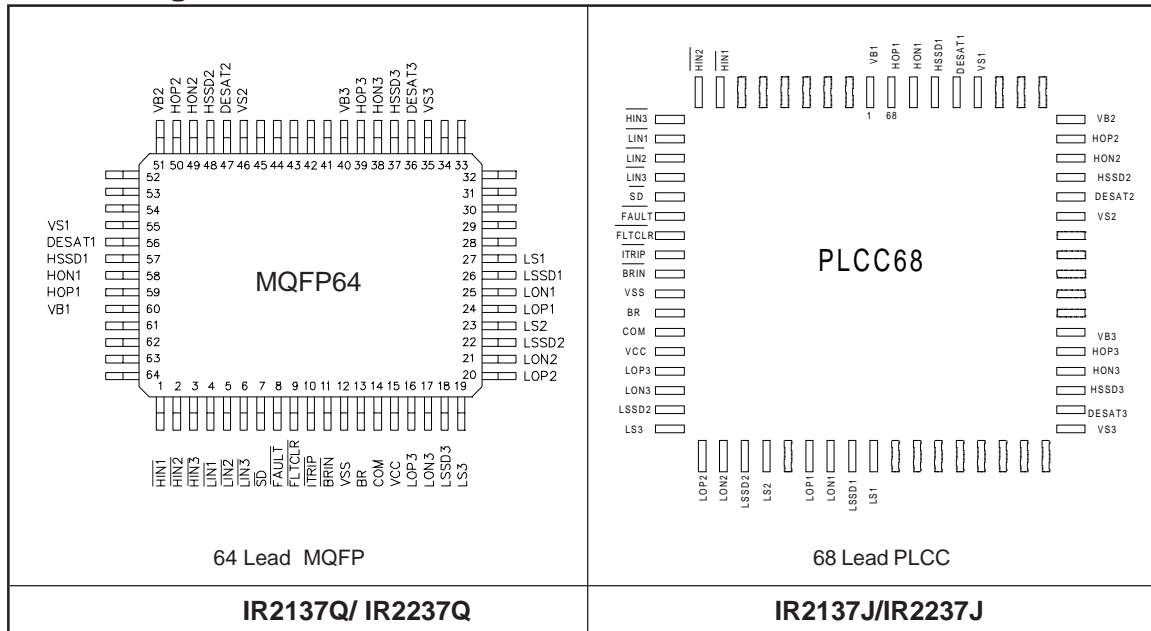


Figure 3. Timing Diagram

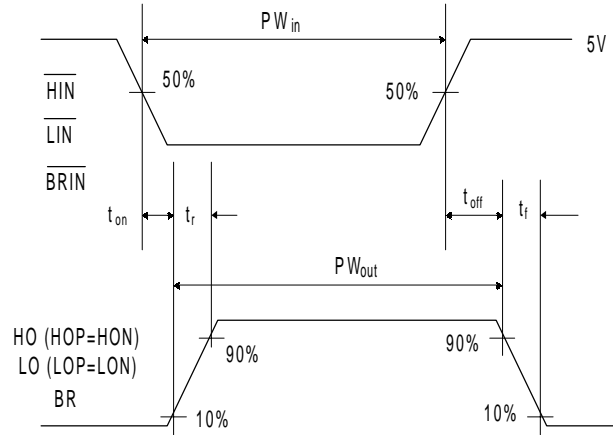


Figure 4. Switching Time Waveforms

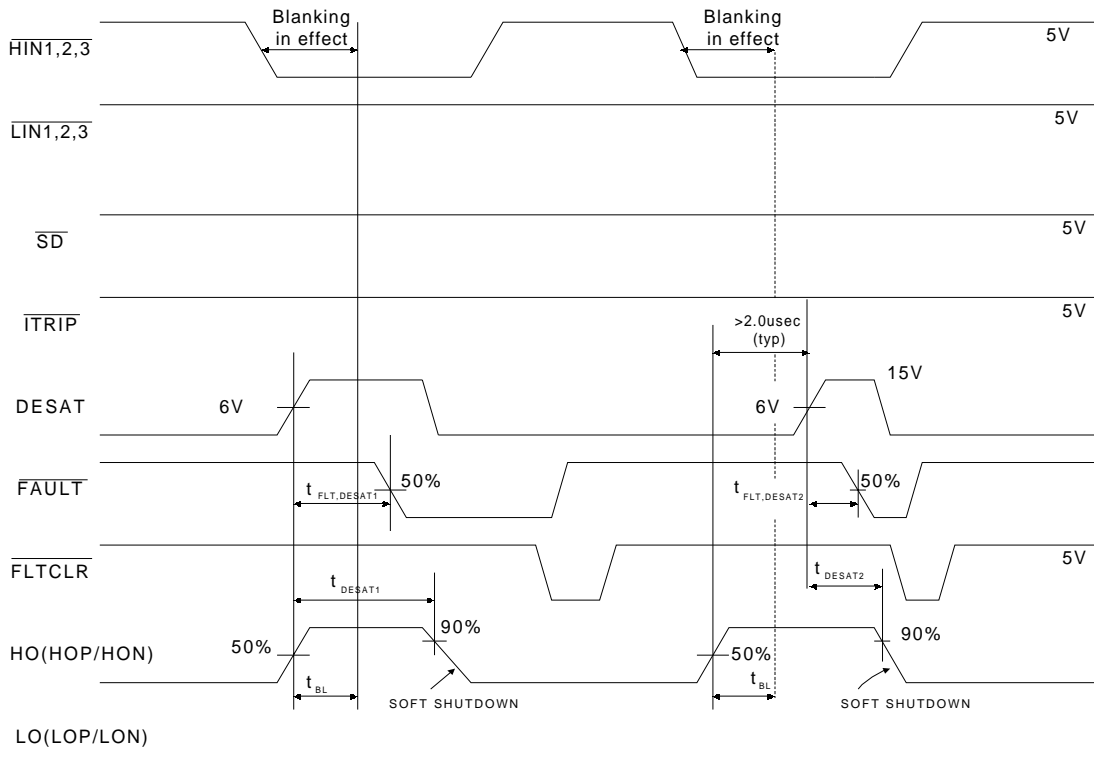


Figure 5. DESAT Timing

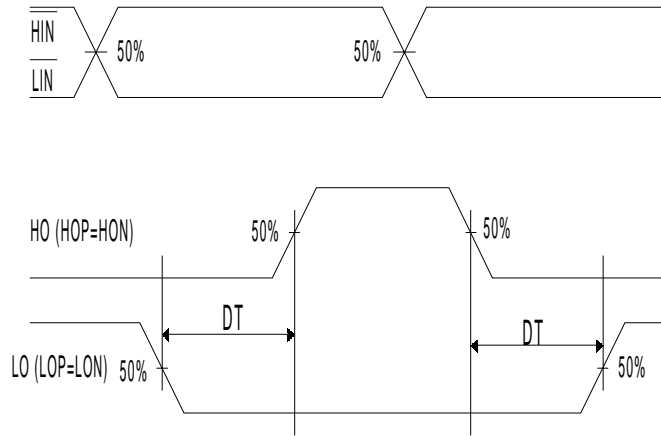


Figure 6. Internal Deadtime Timing

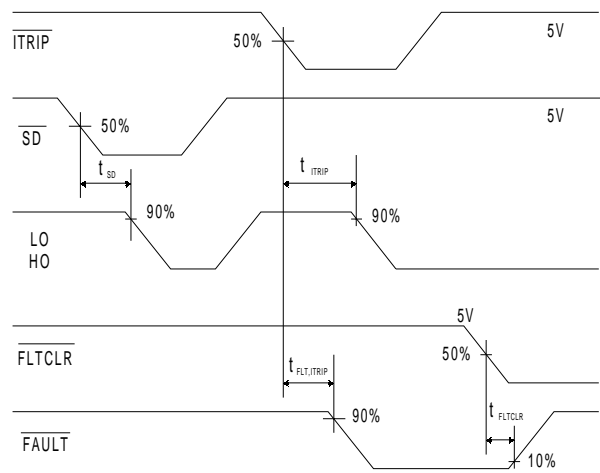
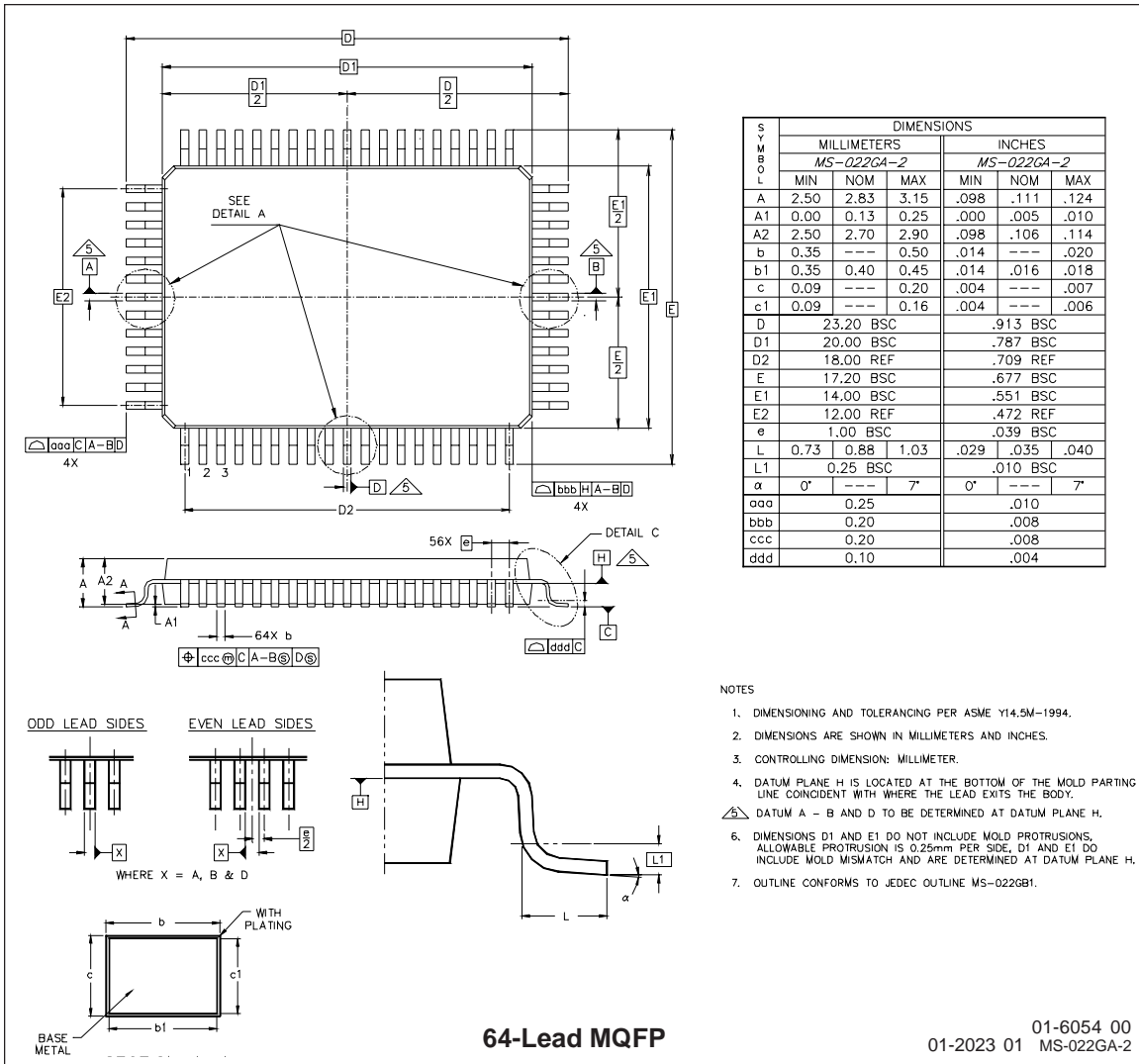


Figure 7. SD, ITRIP Timing

Case outlines



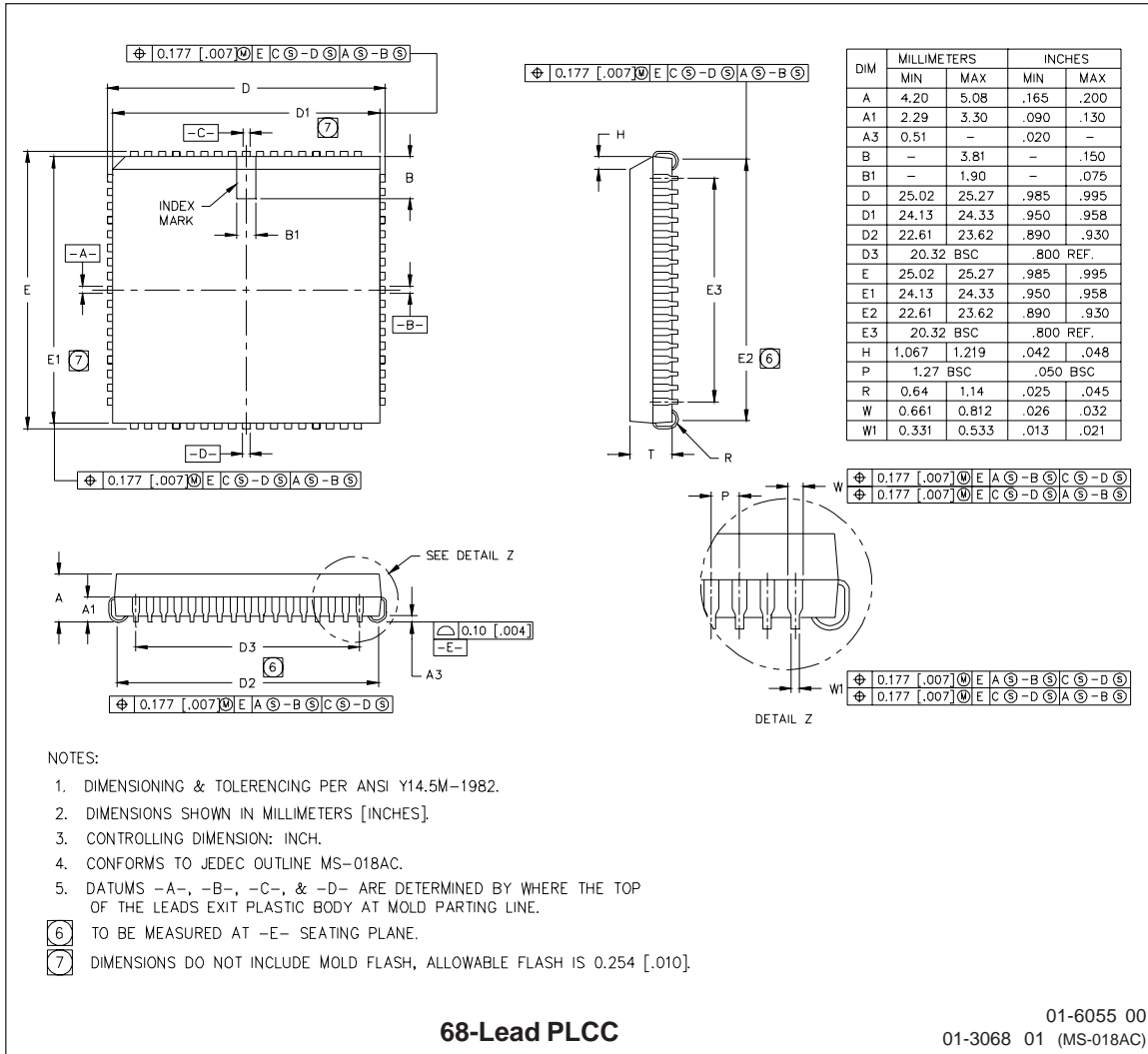
SYMBOL	DIMENSIONS					
	MILLIMETERS			INCHES		
	MS-022GA-2			MS-022GA-2		
	MIN	NOM	MAX	MIN	NOM	MAX
A	2.50	2.83	3.15	.098	.111	.124
A1	0.00	0.13	0.25	.000	.005	.010
A2	2.50	2.70	2.90	.098	.106	.114
b	0.35	---	0.50	.014	---	.020
b1	0.35	0.40	0.45	.014	.016	.018
c	0.09	---	0.20	.004	---	.007
c1	0.09	---	0.16	.004	---	.006
D	23.20 BSC			.913 BSC		
D1	20.00 BSC			.787 BSC		
D2	18.00 REF			.709 REF		
E	17.20 BSC			.677 BSC		
E1	14.00 BSC			.551 BSC		
E2	12.00 REF			.472 REF		
e	1.00 BSC			.039 BSC		
L	0.73	0.88	1.03	.029	.035	.040
L1	0.25 BSC			.010 BSC		
α	0° --- 7°			0° --- 7°		
aaa	0.25			.010		
bbb	0.20			.008		
ccc	0.20			.008		
ddd	0.10			.004		

- NOTES
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 2. DIMENSIONS ARE SHOWN IN MILLIMETERS AND INCHES.
 3. CONTROLLING DIMENSION: MILLIMETER.
 4. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
 5. DATUM A - B AND D TO BE DETERMINED AT DATUM PLANE H.
 6. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSIONS. ALLOWABLE PROTRUSION IS 0.25mm PER SIDE. D1 AND E1 DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
 7. OUTLINE CONFORMS TO JEDEC OUTLINE MS-022GB1.

01-6054 00
01-2023 01 MS-022GA-2

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International
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Data and specifications subject to change without notice. 5/22/2001